## **CNZ1414A** (ON1414A)

## Integrated Photosensor

### Overview

CNZ1414A is ultraminiature, highly reliable transmissive photosensor that has a high efficiency GaAs infrared light emitting diode chip and a low voltage operation type high sensitivity Siintegrated-photodetector chip wich are in a double molded resin package.

#### Features

• Ultraminiature : 4.2 × 4.2 mm (height : 5.2 mm)

• Low voltage operation, low current consumption  $(V_{CC} = 2.2 \text{ to } 7 \text{ V}, I_{CCL} = 0.8 \text{ mA typ.})$ 

• Fast response :  $t_{PHL} = 3 \mu s$ ,  $t_{PLH} = 8 \mu s$  (typ.)

• Highly precise position detection (slit width: 0.3 mm)

• Gap width: 1.2 mm

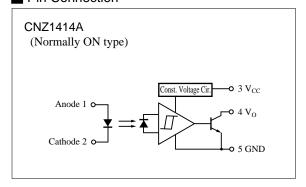
• With attachment positioning pin

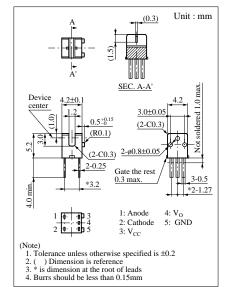
### Absolute Maximum Ratings ( $Ta = 25^{\circ}C$ )

	Symbol	Ratings	Unit	
Input (Light emitting diode)	Reverse voltage (DC)	$V_R$	6	V
	Forward current (DC)	$I_F$	50	mA
	Power dissipation	$P_D^{*1}$	75	mW
Output (Photo IC)	Output current	Io	8	mA
	Output voltage	Vo	12	V
	Supply voltage	V <sub>CC</sub>	7	V
	Power dissipation	$P_{C}^{*2}$	80	mW
Temperature	Operating ambient temperature	Topr	-25 to +85	°C
	Storage temperature	T <sub>stg</sub>	– 40 to +100	°C

<sup>\*1</sup> Input power derating ratio is 1.0 mW/°C at Ta ≥ 25°C.

#### ■ Pin Connection





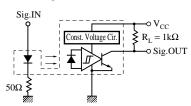
Note) The part number in the parenthesis shows conventional part number.

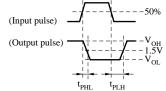
<sup>\*2</sup> Output power derating ratio is 1.07 mW/°C at Ta  $\geq$  25°C.

### ■ Electrical Characteristics (Ta = 25°C)

Parameter		Symbol	Conditions	min	typ	max	Unit
Input characteristics	Forward voltage (DC)	$V_F$	$I_F = 20 \text{mA}$		1.2	1.4	V
	Reverse current (DC)	$I_R$	$V_R = 3V$			10	μА
Output characteristics	"H" Output current	I <sub>OH</sub>	$V_{CC} = 5V, V_{OH} = 12V, I_F = 0mA$			100	μА
	"L" Output voltage	V <sub>OL</sub>	$V_{CC} = 5V, I_{OL} = 5mA, I_F = 2mA$		0.15	0.4	V
	Operating power voltage	V <sub>CC</sub>		2.2		7	V
	"L" Supply current	I <sub>CCL</sub>	$V_{CC} = 5V$ , $I_F = 2mA$		0.8	2	mA
	"H" Supply current	$I_{CCH}$	$V_{CC} = 5V$ , $I_F = 0mA$		0.8	2	mA
Transfer characteristics	Threshold input current	$I_{FH \rightarrow L}$	$V_{CC} = 2.2V$			2	mA
	Hysteresis	$I_{\rm FLH}/I_{\rm FHL}$	$V_{CC} = 2.2V$		0.85		
		t <sub>PHL</sub> *	$V_{CC} = 5V$ , $I_F = 2mA$ , $R_L = 1k\Omega$		3		μs
	Response time	t <sub>PLH</sub> *			8		μs

<sup>\*</sup> Switching time measurement circuit

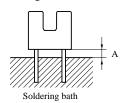




 $t_{PHL}: H \rightarrow L$  Propagation time  $t_{PLH}: L \rightarrow H$  Propagation time

#### • Important Information for Soldering

#### 1. Soldering Position



A: Make sure the distance is 0.1 mm or more.

#### 2. Solder Temperature and Soldering Time

Temperature : 260°C or less Time : within 3 seconds

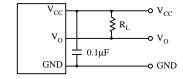
Note) Avoid using reflow soldering methods.

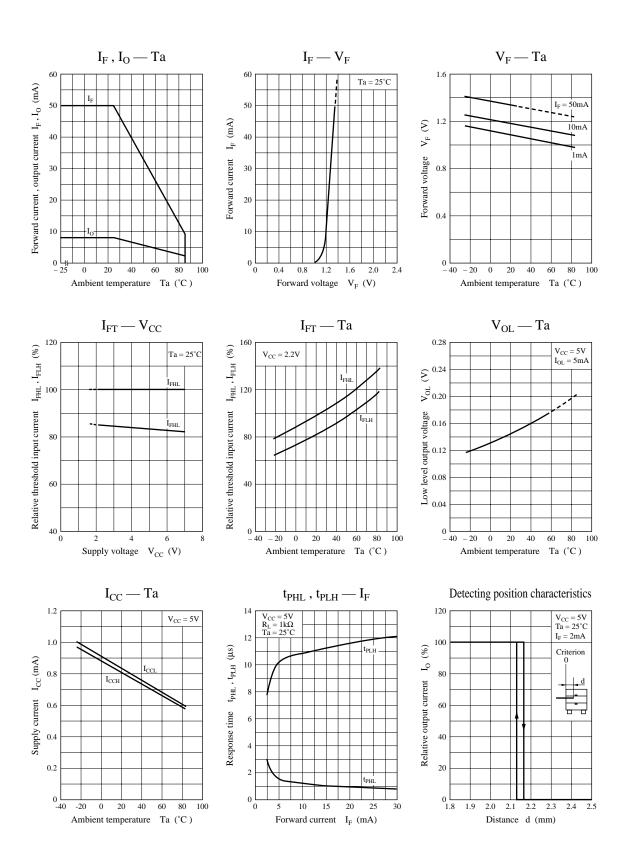
#### 3. Other Issues

- 1) Soldering should not create excessive thermal or mechanical stress on the case package or leads. Excessive stress may cause changes in the shape or characteristics of the package or leads.
- Be careful not to allow solder, flux, solvents, etc. to remain on the case package. Doing so may cause problems related to transmission characteristics, etc.

#### • Important Information Related to Power Source Voltage

In order to stabilize the power line, use a decoupling capacitor of approximately 0.1  $\mu F$  between  $V_{\rm CC}$  and the GND line near the device .





# Caution for Safety



## Gallium arsenide material (GaAs) is used in this product.

Therefore, do not burn, destroy, cut, crush, or chemically decompose the product, since gallium arsenide material in powder or vapor form is harmful to human health

Observe the relevant laws and regulations when disposing of the products. Do not mix them with ordinary industrial waste or household refuse when disposing of GaAs-containing products.

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